Willkommen bei O-Leading

O-Leading ist bestrebt, Ihr One-Stop-Lösungspartner in der EMS-Lieferkette zu sein, einschließlich Leiterplattendesign, Leiterplattenherstellung und Leiterplattenbestückung (PCB Assembly, PCBA) Wir können vom schnellen Drehungsprototyp zur mittleren u. Massenproduktion stützen.

| Impedanz PCB | Hersteller China |

Generell sind unsere globalen Kunden von unseren Dienstleistungen sehr beeindruckt: schnelle Reaktion, wettbewerbsfähiger Preis und Qualitätsverpflichtung. Die Bereitstellung von mehr wertvollem technischen Service und Gesamtlösung ist der Weg, den O nach vorne weist.

Mit Blick auf die Zukunft wird sich O-Lead wie immer auf die Innovation und Entwicklung der Technologie für die Elektronikfertigung konzentrieren und beharrliche Anstrengungen unternehmen, um erstklassigen Service zu bieten und mehr Wert für unsere Kunden zu schaffen.

Produktbeschreibung

• Double Side PCB Hersteller China

PCB P / N	0310303500E
Ebenenzahl	2L
Material	FR-4 TG130
Verpflegung thk	0,8 mm
kupfer thk	1 / 1oz
Kleinste Lochgröße	0,2 mm
Anzahl Löcher (Stk)	23
Linie w / s	8 / 8mil
Impedanzkontrolle. J / N (Tol%)	N
Oberflächenveredelung	ENIG Au: 0.05-0.10UM
Lötmaske Siebdruck	Grün / n / a
Single Board Größe	Abmessung X (mm): 139; Dim Y (mm): 75
Panelisation	Abmessung X (mm): 236,5; Abmessung Y (mm): 137,2; Anzahl der UPS: 4
Besondere	N
Fräsen / Stanzen	CNC

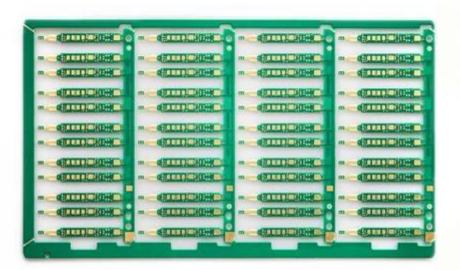












www.o-leading.com

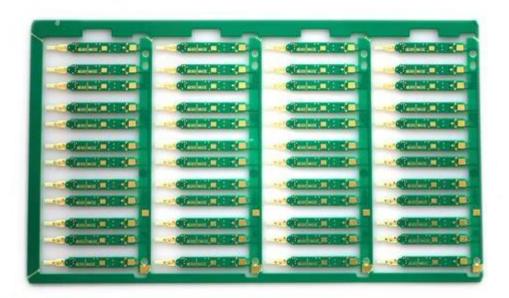












www.o-leading.com

Unser Team



Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

Factory SMT













Zertifizierungen







Test Report

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

No. SZXEC1900530401

1313,FLOOR 13, FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG, CHINA

Date: 30 Mar 2019 Page 1 of 6

Test Report No. SZXEC1900530401 Date: 30 Mar 2019 Page 2 of 6

Test Results :

Test Part Description :

 Specimen No.
 SGS Sample ID
 Description

 SN1
 SZX19-005304.001
 Green*PCB**

(1) 1 mg/kg = 1 ppm = 0.0001% (2) MDL = Method Detection Limit

(3) ND = Not Detected (< MDL)

(4) "-" = Not Regulated

RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC682321-5:2013, IEC62321-7:2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s)	Limit	Unit	MDL	001
Cadmium (Cd)	100	mg/kg	2	ND
Lead (Pb)	1,000	mg/kg	2	8
Mercury (Hg)	1,000	mg/kg	2	ND
Hexavalent Chromium (Cr(VI))	1,000	mg/kg	8	ND
Sum of PBBs	1.000	mg/kg		ND
Monobromobiphenyl		mg/kg	5	ND
Dibromobiphenyl	12	mg/kg	5	ND
Tribromobiphenyl	15	mg/kg	5	ND
Tetrabromobiphenyl		mg/kg	5	ND
Pentabromobiphenyl		mg/kg	5	ND
Hexabromobiphenyl		mg/kg	5	ND
Heptabromobiphenyl		mg/kg	5	ND
Octabromobiphenyl		mg/kg	5	ND
Nonabromobiphenyl	6	mg/kg	5	ND
Decabromobiphenyl		mg/kg	5	ND
Sum of PBDEs	1,000	mg/kg		ND
Monobromodiphenyl ether		mg/kg	5	ND
Dibromodiphenyl ether	12	mg/kg	5	ND
Tribromodiphenyl ether	2	mg/kg	5	ND
Tetrabromodiphenyl ether	-	mg/kg	5	ND
Pentabromodiphenyl ether		mg/kg	5	ND



in writing, this document is issued by the Company subject to its General Conditions of Service as for accessible at high civere ass convent forms and Conditions again and for electronic ternal doc fishors for Electronic Documents is inter/investage.com/lent ferms end-Conditions[Ferms-e]-Documents missiants of labelity, independentation and jurisdiction insues defined therein, any folder of this docu-

- Remark (14.0 post-times-days-scene)
(2586g to 4.1 post-times-form) (14.0 post-times-for

Member of the SGS Group (SGS SA)

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : RP19-005089 - SZ Date of Sample Received : 22 Mar 2019

22 Mar 2019 - 30 Mar 2019 Testing Period :

Test Requested : Selected test(s) as requested by client. Test Method Please refer to next page(s).

Test Results : Please refer to next page(s).

Conclusion:

Based on the performed tests on submitted sample(s), the results of Lead. Mercury, Cadmium, Hexavalent chiromium, Polybrominated biphenyls (PBBs), Polybrominated diphenyl ethers (PBBcs) and Phthalates such as Bis(2-ethylbexyl) phthalate (DBFP). Bibutyl phthalate (DBFP). Tolbutyl phthalate (DBFP), and Diisobutyl phthalate (DBFP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/85/EU.

Signed for and on behalf of SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

lina

Tina Fan Approved Signatory



Max

Max

UL Product iQ™



ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

Wiring, Printed - Component

See General Information for Wiring, Printed - Component

Cond Width

O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F TAI SANG BANK BLDG 130-132 DES VOEUS ROAD CENTRAL, HONG KONG

		Min	Cond	SS/	Area	Solo	der	Oper		Meets	c
	Min	Edge	Thk	DS/	Diam	Lim	its	Temp	Flame	UL796	T
Type	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	c	sec	c	Class	DSR	1
Multilayer (m	Multilayer (mass laminate) printed wiring boards.										
O-LEADING- 401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	3	50
O-LEADING- 407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer pri	nted wiring bo	ards.							3		
O-LEADING- 408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer p	rinted wiring b	oards.							3 77	7.57	
O-LEADING- 002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING- 003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	A	-
O-LEADING- 033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	*
O-LEADING- 205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING- 206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	-
O-LEADING- D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING- S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING- S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	НВ	A	*
O-LEADING- S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

 $[\]mbox{\ensuremath{\star}}$ - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

并不是所有出现在本数据库中的公司名称和产品都满足了UL 跟踪检验服务的要求。只有带有 UL 标志的产品,才应该被视为经过UL认证,并满足UL 跟踪检验服务的要求。注意查看产品上的标志。

UL 允许在线认证目录中所含材料的复制遵循以下条件: 1.指南信息、装配、构造、设计、系统和/或认证(文件)必须在不篡攻任何数据(或图纸)的情况下完整且无误导性地呈现。2."经 UL 允许从在线认证目录转载"声明必须出现在所摘取材料的邻近位置。此外,转载材料必须包含以下格式的版权声明:"© 2019 UL LLC"

Verpackung & Lieferung

Shipping service











	Quick Turn Lead Time					
Layer Count:	Lead Tim	Special Requirement				
1L/2L	2-3days	24 Hours,48 Hours				
4L	3-4days	48 Hours				
6L	4-5days	72 Hours				
8L	5-6days	NA				
10L	6-7days	NA				
12L	7-8days	NA				
14L	8-9days	NA				

	Standard Lead Time					
Layer Count:	Sample Lead Time	Volume order lead time				
2L	4 days	10 days				
4L	5 days	11 days				
6L	6 days	12 days				
8L	8 days	14 days				
10L	10 days	16 days				
12L	12 days	18 days				
14L	14 days	20 days				
16-32L	18 days	24 days				

Prozessfähigkeit

PCB-Produktionsmöglichkeiten

Schicht Anzahl: 1Layer-32Layer Fertige Kupferdicke: 1 / 3oz-12oz

Min. Linienbreite / interner Abstand: 3,0 mil / 3,0 mil Min. Linienbreite / Abstand extern: 4.0mil / 4.0mil

Maximales Seitenverhältnis: 10: 1

Brettstärke: 0.2mm-5.0mm

Max Panel Größe (Zoll): 635 * 1500 mm

Mindestbohrlochgröße: 4mil Plated Hole Tolerance: +/- 3mil Blind / Buried Vias (All-Typen): JA Via Fill (leitend, nicht leitend): JA

Basismaterial: FR-4, FR-4high Tg. Halogenfreies Material, Rogers, Aluminiumbasis, Polyimid,

Schweres Kupfer

Oberflächen: HASL, OSP, ENIG, HAL-LF, Versilberung, Immersionsdose, Goldfinger, Kohletinte

SMT-Produktionsmöglichkeiten

Leiterplattenmaterial: FR-4, CEM-1, CEM-3, Leiterplatte auf Aluminiumbasis

Maximale Leiterplattengröße: 510 x 460 mm

Min PCB Größe: 50x50mm PWB-Stärke: 0.5mm-4.5mm Brettstärke: 0.5-4mm

Min. Komponentengröße: 0201

Komponente mit Standardchipgröße: 0603 und größer

Maximale Höhe der Komponente: 15 mm

Min. Steigung: 0,3 mm

Min. BGA-Kugelpitch: 0,4 mm

Platzierungsgenauigkeit: +/- 0,03 mm